

**IN THE CLAIMS**

Claims 1-20: Previously Canceled.

21. (Currently Amended) A method for producing an electronic component, comprising:  
providing a substrate layer;  
providing a solid, substantially planar polymer-based optical wave-guide, wherein the wave-guide is photobleached or doped; and  
laminating the solid, substantially planar optical wave-guide onto the substrate layer.
22. (Previously Presented) The method of claim 21, wherein at least one of a laminating material or a cladding material is coupled to the wave-guide.
23. (Previously Presented) The method of claim 22, wherein at least one of an additional layer is coupled to the laminating material or the cladding material.
24. (Currently Amended) The method of claim 21, wherein providing the optical wave-guide further comprises etching or molding a silicon-based material to produce the wave-guide.
25. (Presently Presented) The method of claim 21, wherein the substrate layer comprises at least two layers of materials.
26. (Previously Presented) The method of claim 25, wherein the at least two materials comprises silica wafers, dielectric materials, adhesive materials, resins, metals, metal alloys, and composite materials.
27. (Previously Presented) The method of claim 21, wherein the wave-guide is a silicon-based material.